IN THE CLAIMS:

Please cancel Claim 6 without prejudice or disclaimer of the subject matter presented therein and without conceding the correctness of its rejection. Please amend Claim 5 as shown below. The claims, as pending in the subject application, read as follows:

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1 to 4. (Cancelled)

5. (Currently Amended) An image pickup apparatus comprising: a lead of a flexible wiring film;

an image pickup element chip electrically connected to the lead at an electrical connection point; and

a cover glass for protecting a surface of the image pickup element chip,

wherein the lead, the image pickup element chip, and the cover glass are sealed with a sealant an ultraviolet-curing resin in a peripheral portion of the image pickup element chip, and

wherein the lead has a hole formed in a portion of the lead in contact with the sealant ultraviolet-curing resin, the portion of the lead being between the electrical connection point and an outer end of the lead, and

wherein a part of the hole is positioned outside the cover glass.

6 and 7. (Cancelled)

- 8. (Previously Presented) The image pickup apparatus according to Claim 5, wherein at least one of a layer for preventing reflection of external light and a layer for preventing multiple reflection is formed between the lead and the cover glass.
- 9. (Previously Presented) An image pickup system comprising:
 the image pickup apparatus according to Claim 5;
 an optical system for focusing light on the image pickup apparatus; and
 a signal processing circuit for processing an output signal from the image
 pickup apparatus.

10 and 11. (Cancelled)